3.2 Matters concerning the preparation before use
The bonding of the main circuit ground when using the module shall be performed after the power source is shut off and all signals and power lines are disconnected. The bonding of the main circuit ground is performed after the power source is shut off for all signals. When shutting down the power source, first disconnect the output signal and then the power source (input power). If the output signal is connected, the power source can be turned off without a malfunction.

3.4 Precautions for Startup and Maintenance
Follow the wiring diagram for the connection of the terminal. Follow the instructions of the manual concerning the connection of the module and the terminal. Please refer to the User’s Manual (Details) for the detailed installation and the detailed specifications of the current sensor and the voltage sensor.

4. Names and Types of LIDs
For the names and functions of each of the LIDs, please refer to the Manual for the product.